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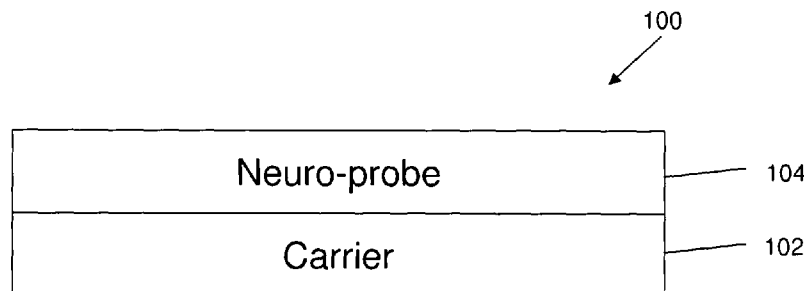
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- (54) **Title:** NEURO-PROBE DEVICE, IMPLANTABLE ELECTRONIC DEVICE AND METHOD OF FORMING A NEURO-PROBE DEVICE



- (57) **Abstract:** A neuro-probe device is provided. The neuro-probe device includes a carrier including bio-resorbable glass, and a neuro-probe mounted on the carrier.

